

LAW OFFICES
SUGHRUE, MION, ZINN, MACPEAK & SEAS, PLLC
2100 PENNSYLVANIA AVENUE, N.W.
WASHINGTON, DC 20037-3213
TELEPHONE (202) 293-7060
FACSIMILE (202) 293-7860
www.sughrue.com

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BOX PCT

Commissioner for Patents
Washington, D.C. 20231

PCT/JP99/02379
-filed May 7, 1999

Re: Application of KAZUNOBU FUJIKAWA, AKIHIRO GOTO
METHOD AND APPARATUS FOR SURFACE DISCHARGE PROCESSING,
AND AN ELECTRODE FOR SURFACE DISCHARGE PROCESSING
Our Ref: Q63075

Dear Sir:

This is a request for a Continuation Application of KAZUNOBU FUJIKAWA and AKIHIRO GOTO pending prior Application No. PCT/JP99/02379 filed May 7, 1999 entitled METHOD AND APPARATUS FOR SURFACE DISCHARGE PROCESSING, AND AN ELECTRODE FOR SURFACE DISCHARGE PROCESSING.

This application is being filed under 37 C.F.R. § 1.53(b). Enclosed is a specification, including the claims and Abstract, 8 sheets of drawings, an executed Declaration/Power of Attorney, the executed Assignment with PTO-1595, the PCT International Search Report and an Information Disclosure Statement, with Form PTO-1449 listing known references.

**PLEASE NOTE: This application is being filed as a
Continuation of PCT/JP99/02379 pursuant to MPEP §§1895 and 1896.**

The Government filing fee is calculated as follows:

Total claims	<u>13</u>	-	<u>20</u>	=	<u></u>	x \$18.00	=	<u>\$0.00</u>
Independent claims	<u>5</u>	-	<u>3</u>	=	<u>2</u>	x \$80.00	=	<u>\$160.00</u>
Base Fee								<u>\$860.00</u>

TOTAL FILING FEE	<u><u>\$1,020.00</u></u>
Recordation of Assignment	<u><u>\$ 40.00</u></u>
TOTAL FEE	<u><u>\$1,060.00</u></u>

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Checks for the statutory filing fee of \$1,020.00 and Assignment recordation fee of \$40.00 are attached. You are also directed and authorized to charge or credit any difference or overpayment to Deposit Account No. 19-4880. The Commissioner is hereby authorized to charge any fees under 37 C.F.R. §§ 1.16, 1.17 and 1.492 which may be required during the entire pendency of the application to Deposit Account No. 19-4880. A duplicate copy of this transmittal letter is attached.

There is no §119 claim to priority.

Respectfully submitted,



Richard C. Turner
Registration No. 29,710

SUGHRUE, MION, ZINN,
MACPEAK & SEAS, PLLC
2100 Pennsylvania Avenue, N.W.
Washington, D.C. 20037-3213
Telephone: (202) 293-7060
Facsimile: (202) 293-7860

Date: February 20, 2001

SPECIFICATION

METHOD AND APPARATUS FOR SURFACE DISCHARGE PROCESSING, AND
AN ELECTRODE FOR SURFACE DISCHARGE PROCESSING

5

TECHNICAL FIELD

The present invention in general relates to an improvement in the surface discharge processing method and apparatus, and a surface discharge processing electrode.

10 More specifically, this invention relates to a technology for generating an electric discharge between an electrode and a workpiece, and forming a surface reforming layer on the surface of the workpiece by the discharge energy.

15 BACKGROUND ART

As a prior art for forming a surface reforming layer on a workpiece by discharge in liquid and providing with corrosion resistance and wear resistance, for example, a surface discharge processing method is disclosed in Japanese

20 Patent Application Laid-open No. 5-148615. This is a two-step surface discharge processing method of metal material. A primary processing (deposit processing) is performed by using a compacted powder electrode formed by compressing WC powder and Co powder. A secondary processing 25 (re-fusing process) is performed by replacing the electrode

with an electrode relatively small in electrode consumption such as copper electrode. In this prior art, a surface reforming layer of high hardness and high adhesion can be formed on a steel material.

5 Japanese Patent Application Laid-open No. 9-192937 discloses a surface discharge processing method of forming a rigid surface reforming layer without re-fusing process on the surface of iron, steel, or cemented carbide. This method makes use of a compacted powder electrode formed by
10 compressing TiH₂ powder.

When such surface discharge processing technology is applied, for example, to the mold, the mold life can be extended notably owing to improvement in corrosion resistance and wear resistance.

15 When such a surface discharge processing is performed on the workpiece by using a molded electrode, as shown in Fig. 8 (a) for example, when a first workpiece 21 is processed by a surface discharge processing electrode 22, a worn portion 22a is formed on the surface discharge processing electrode 22 and a surface reforming layer 23 is formed on the first workpiece 21. When a second workpiece 24 different in size from the first workpiece 21 is processed by the same surface discharge processing electrode 22 as used in surface discharge processing of the first workpiece 21, as shown
20 in Fig. 8 (b), worn portions 22b, 22c are formed on the surface
25 in Fig. 8 (b), worn portions 22b, 22c are formed on the surface

discharge processing electrode 22, and a surface reforming layer 25 is formed on the second workpiece 24. The thickness of the surface reforming layer 25 is uneven as shown in Fig. 8 (b), and uniform surface reforming layer cannot be formed.

5 In addition, multiple electrodes suited to the processing shapes must be prepared.

To solve these problems, it may be considered to use the surface reforming material or a raw material for the surface reforming material as the wire electrode itself,
10 and process the discharge surface of the workpiece by using this wire electrode. However, for example, when Ti or W is used as wire electrode, it is not practical because the surface discharge processing speed is too slow. Furthermore, if the wire electrode is formed by using
15 compacted powder, the tensile strength of the wire electrode is not guaranteed, and it is completely impracticable.

DISCLOSURE OF THE INVENTION

The invention is intended to solve the conventional
20 problems, and it is hence an object thereof to attain surface discharge processing method and apparatus and surface discharge processing electrode, suited to partial surface reforming of mold or the like, capable of forming a uniform surface reforming layer on the workpiece, not required to
25 prepare multiple electrodes according to the processing

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shapes, and capable of keeping a practical surface discharge processing speed.

In a surface discharge processing method according to a first aspect of the invention, the surface discharge processing electrode is a wire electrode composed of a core wire made of ductile material, and a surface discharge processing material made of a surface reforming material adhered to this core wire or a raw material for the surface reforming material.

10 A surface discharge processing method according to a second aspect of the invention relates to the surface discharge processing method of the first aspect of the invention, in which a recess is formed in the core wire, and the surface discharge processing material is adhered
15 to this recess.

A surface discharge processing method according to a third aspect of the invention relates to the surface discharge processing method of the second aspect of the invention, in which the recess formed in the core wire is
20 spiral in shape.

A surface discharge processing method according to a fourth aspect of the invention relates to the surface discharge processing method of the first aspect of the invention, in which the processing program for performing
25 the surface discharge processing is the processing program

for wire discharge processing employed in a preparatory step of surface discharge processing.

In a surface discharge processing method according to a fifth aspect of the invention, a first wire electrode for removal processing by discharge, and a second wire electrode for surface discharge processing composed of a core wire made of ductile material, and a surface discharge processing material made of a surface reforming material adhered to this core wire or a raw material for the surface reforming material are changed over, and the processing is done by combination of removal processing of the workpiece, and surface discharge processing for reforming the surface of the processed side formed by this removal process.

A surface discharge processing apparatus according to a sixth aspect of the invention comprises a wire electrode used as the surface discharge processing electrode, and a wire electrode feeder for feeding the wire electrode to the workpiece. The wire electrode is composed of a core wire made of ductile material and a surface discharge processing material. The discharge processing material is made of a surface reforming material adhered to the core wire or a raw material for the surface reforming material.

A surface discharge processing apparatus according to a seventh aspect of the invention relates to the surface discharge processing apparatus of the sixth aspect of the

invention, in which a recess is formed in the core wire, and the surface discharge processing material is adhered to this recess.

A surface discharge processing apparatus according
5 to an eighth aspect of the invention relates to the surface discharge processing apparatus of the seventh aspect of the invention, in which the recess formed in the core wire is spiral in shape.

A surface discharge processing apparatus according
10 to a ninth aspect of the invention relates to the surface discharge processing apparatus of the sixth aspect of the invention, in which the processing program for performing the surface discharge processing is the processing program for wire discharge processing employed in a preparatory step
15 of surface discharge processing.

A surface discharge processing apparatus according to a tenth aspect of the invention comprises a first wire electrode for removal processing by discharge, a second wire electrode for surface discharge processing composed of a
20 core wire made of ductile material, and a surface discharge processing material made of a surface reforming material adhered to this core wire or a raw material for the surface reforming material, a wire electrode feeder for feeding the first wire electrode and second wire electrode to the
25 workpiece, and a wire electrode changeover unit which changes

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over the first wire electrode and second wire electrode.

In a surface discharge processing electrode according to an eleventh aspect of the invention, the surface discharge processing electrode is composed of a core wire made of 5 ductile material, and a surface discharge processing material made of a surface reforming material adhered to this core wire or a raw material for the surface reforming material.

A surface discharge processing electrode according 10 to a twelfth aspect of the invention relates to the surface discharge processing electrode of the eleventh aspect of the invention, in which a recess is formed in the core wire, and the surface discharge processing material is adhered to this recess.

15 A surface discharge processing electrode according to a thirteenth aspect of the invention relates to the surface discharge processing electrode of the twelfth aspect of the invention, in which the recess formed in the core wire is spiral in shape.

20 Having such structure as mentioned above, the invention brings about the following effects.

In the first aspect of the invention, the tensile strength of the wire electrode for surface discharge processing necessary for the processing work can be obtained 25 by the strength of the core wire, and the surface reforming

layer of a specific characteristic can be formed on the workpiece by the surface discharge processing material adhered to the core wire at a practical surface discharge processing speed. Besides, it is not necessary to prepare 5 multiple electrodes according to processing shapes.

In the second aspect of the invention, in addition to the effects as in the first aspect of the invention, the fixing stability of surface discharge processing material on the core can be enhanced in the wire feeding process.

10 In the third aspect of the invention, in addition to the effects as in the second aspect of the invention, the surface reforming layer can be formed uniformly and stably on the workpiece.

15 In the fourth aspect of the invention, in addition to the effects as in the first aspect of the invention, the electrode path program for surface discharge processing can be created easily, and the preparation time for processing can be shortened.

20 In the fifth aspect of the invention, the tensile strength of the wire electrode for surface discharge processing necessary for the processing work can be obtained by the strength of the core wire, and the surface reforming layer of a specific characteristic can be formed on the workpiece by the surface discharge processing material 25 adhered to the core wire at a practical surface discharge

processing speed. Besides, it is not necessary to prepare multiple electrodes according to processing shapes. In addition, since the removal process of the workpiece and the surface discharge processing for reforming the surface 5 of the processed side formed by this removal process can be done in the same preparatory step, the preparation time for workpiece shape processing and surface discharge processing can be shortened substantially.

In the sixth aspect of the invention, the same effects 10 as in the first aspect of the invention are obtained.

In the seventh aspect of the invention, the same effects as in the second aspect of the invention are obtained.

In the eighth aspect of the invention, the same effects as in the third aspect of the invention are obtained.

15 In the ninth aspect of the invention, the same effects as in the fourth aspect of the invention are obtained.

In the tenth aspect of the invention, the same effects as in the fifth aspect of the invention are obtained.

In the eleventh aspect of the invention, the same 20 effects as in the first aspect of the invention are obtained, in surface discharge processing by using the surface discharge processing electrode of the invention.

In the twelfth aspect of the invention, the same effects as in the second aspect of the invention are obtained, in 25 surface discharge processing by using the surface discharge

processing electrode of the invention.

In the thirteenth aspect of the invention, the same effects as in the third aspect of the invention are obtained, in surface discharge processing by using the surface
5 discharge processing electrode of the invention.

BRIEF DESCRIPTION OF THE DRAWINGS

Fig. 1 is structural diagram showing a surface discharge processing apparatus in a first embodiment of the
10 invention; Fig. 2 is a sectional view showing the structure of a wire electrode for surface discharge processing in the first embodiment of the invention; Fig. 3 is a side view showing the structure of the wire electrode for surface discharge processing in the first embodiment of the
15 invention; Fig. 4 is an explanatory diagram of a method of surface discharge processing in a cutting edge side portion of the workpiece in the first embodiment of the invention;
Fig. 5 is structural diagram showing a surface discharge processing apparatus in a second embodiment of the invention;
20 Fig. 6 is an explanatory diagram of an example of structure of a wire electrode changeover unit in the second embodiment of the invention; Fig. 7 is an explanatory diagram of electrode moving path in the second embodiment of the invention; and Fig. 8 is an explanatory diagram showing a
25 conventional discharge electrode processing method.

BEST MODE FOR CARRYING OUT THE INVENTION

First Embodiment:

Fig. 1 is structural diagram showing a surface discharge processing apparatus in a first embodiment of the invention. Legend 1 denotes a workpiece, legend 2 denotes a wire electrode for surface discharge processing, legend 3 denotes a feed reel for feeding the wire electrode 2, legend 4 denotes a takeup reel for collecting the wire electrode, legend 5 denotes a platen for fixing the workpiece 1, legend 6 denotes an X-table for driving the workpiece 1 in a horizontal direction (X-axis direction), legend 7 denotes a Y-table for driving the workpiece 1 in a horizontal direction (Y-axis direction), legend 8 denotes an X-axis servo amplifier for a not shown X-axis drive motor which drives the X-table 6, legend 9 denotes a Y-axis servo amplifier for a not shown Y-axis drive motor which drives Y-table 7, legend 10 denotes a coolant, legend 11 denotes a coolant nozzle through which the coolant 10 is injected, legend 12 denotes an NC unit, legend 13 denotes a locus move control unit provided in the NC unit 12 for controlling relative move of the wire electrode 2 for surface discharge processing and the workpiece 1, and legend 14 denotes a CAM system for generating electrode move locus for supplying an electrode path program (NC program) for processing by

the wire electrode 2 for surface discharge processing into the locus move control unit 13. The wire electrode 2 for surface discharge processing is fed onto the workpiece 1 by a wire electrode feeder composed of the feed reel 3, takeup reel 4 and others, and a surface reforming layer is formed on the workpiece by the discharge between the wire electrode 2 for surface discharge processing and the workpiece 1.

The wire electrode 2 for surface discharge processing is composed of a core wire 2a and a surface discharge processing material 2b as shown in a sectional view in Fig. 2, and the core wire 2a is made of brass or other ductile material. The surface discharge processing material 2b is made of a surface reforming material or a raw material for surface reforming material. This surface discharge processing material 2b is adhered to the core wire 2a by coating, dipping, plating, or pressing. Alternatively, the surface discharge processing material 2b may be mixed in a conductive paint, and applied to the core wire 2a. In this case, as shown in Fig. 2 (b), by forming a recess in the core wire 2a, and adhering the surface discharge processing material 2b to this recess, the fixing stability of the surface discharge processing material 2b on the core wire 2a may be enhanced in the wire feed process. The shape of the recess to be formed in the core 2a is not limited to the shape and number of recesses shown in Fig. 2 (b),

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but may be formed in any shape or number so as to be capable of enhancing the fixing stability of the surface discharge processing material 2b on the core wire 2a.

Fig. 3 is a side view of the wire electrode 2 for surface discharge processing, in which Fig. 3 (a) corresponds to the sectional view shown in fig. 2 (a), and Fig. 3 (b) to (e) correspond to the sectional view shown in Fig. 2 (b). A spiral recess may be formed in the core wire 2a as shown in Fig. 3 (c). In this case, the fixing stability of the surface discharge processing material 2b on the core wire 2a is enhanced in the wire feed process as mentioned above, and moreover the surface reforming layer can be formed more uniformly and stably on the workpiece 1.

By using the wire electrode 2 for surface discharge processing having such composition, the tensile strength of the wire electrode 2 for surface discharge processing necessary for the processing work can be obtained by the strength of the core wire 2a. Furthermore, the surface reforming layer of a specific characteristic can be formed 20 on the workpiece 1 by the surface discharge processing material 2b adhered to the core wire 2a at a practical surface discharge processing speed.

The operation in surface discharge processing of the workpiece 1 is explained below. It is assumed that the 25 workpiece 1 is a press mold. Furthermore, it is assumed

that, before the step of surface discharge processing, the workpiece 1 is processed by grinding or wire discharge processing, and the shape as the cutting edge of the press mold has been already formed. In Fig. 1, the workpiece 1
5 is put and fixed on the platen 5. The wire electrode 2 for surface discharge processing is set in place, and surface discharge processing is started. Resultantly, a hard surface reforming layer is formed on the cutting edge side surface of the workpiece 1. For this purpose, the wire
10 electrode 2 for surface discharge processing must be controlled so as to move along the cutting edge profile of the workpiece 1. The locus move control unit 13 provided in the NC unit 12 drives and controls the X-table 6 and Y-table 7 according to the electrode path information preliminarily
15 created by the CAM device 14 for generating electrode move locus, moves the wire electrode 2 for surface discharge processing and workpiece 1 relatively in the horizontal direction, and controls the locus move of the wire electrode 2 for surface discharge processing so as to copy the cutting
20 edge profile of the workpiece 1.

Fig. 4 is an explanatory diagram of method of surface discharge processing on the cutting edge side portion 1a of the workpiece 1. As the surface discharge processing progresses, the wire electrode 2 for surface discharge processing is consumed. However, since the wire electrode
25

2 for surface discharge processing is fed by the feed reel
3 shown in Fig. 1, it is possible to always perform the surface
discharge processing with a fresh (non-consumed) wire
electrode 2 for surface discharge processing. Therefore,
5 the electrode movement (P in Fig. 4) of the wire electrode
2 for surface discharge processing may be same as the
electrode move path in wire discharge processing. Thus,
by performing surface discharge processing by moving the
wire electrode 2 for surface discharge processing so as to
10 copy the cutting edge profile of the workpiece 1, a hard
surface reforming layer 15 can be formed in the cutting edge
side portion 1a of the workpiece 1.

In this method, a hard surface reforming layer is formed
by surface discharge processing on the cutting edge side
15 portion of a blanking mold, and a press blanking test was
conducted, and, as a result, as compared with the case not
performing surface discharge processing, the shear droop
of the pressed work after 400000 shots was less than half,
and the mold life was extended.

20 Not only in such blanking mold, but also in other shapes
that can be processed by wire discharge processing
(two-dimensional shape, envelope shape), for example,
extrusion mold, punch, drill and other cutting edges, the
surface discharge processing of the invention can be applied,
25 and same effects are obtained.

Further, as the electrode path program of surface discharge processing, by using the processing program of wire discharge processing employed at a preparatory step of the workpiece 1, the electrode path program for surface discharge processing can be created easily, and the time required for preparation of the process can be shortened.

5 Second Embodiment:

Fig. 5 is structural diagram showing a surface discharge processing apparatus in a second embodiment of the invention. Same or corresponding parts as in the first embodiment shown in Fig. 1 are provided with the same legends. In Fig. 5, legend 16 denotes a wire electrode for wire discharge processing used in ordinary removal process, legend 17 denotes a feed reel, and legend 18 denotes a wire electrode changeover unit for changing over between the wire electrode 2 for surface discharge processing and the wire electrode 16 for wire discharge processing, depending on the type of processing work. Fig. 6 is an explanatory diagram showing an example of structure of the wire electrode changeover unit 18. Legend 19 denotes a wire fixing unit, and legend 20 denotes a wire cutting device. After processing by the wire electrode 16 for wire discharge processing as shown in Fig. 6 (a), the wire electrode 16 for wire discharge processing is cut off by the wire cutting device 20 as shown in Fig. 6 (b). Next, as shown in Fig.

6 (c), the wire electrode changeover unit 18 is moved in
a direction A shown by an arrow in the diagram by means of
a not shown drive device, and the wire electrode 2 for surface
discharge processing is fed and loaded in direction B in
5 the diagram. The operation is same when changing over from
the wire electrode 2 for surface discharge processing to
the wire electrode 16 for wire discharge processing.

The processing of the workpiece 1 will be now explained.
It is assumed that the workpiece 1 is a press mold. Referring
10 to Fig. 5, the workpiece 1 is put and fixed on the platen
5. The wire electrode 16 for wire discharge processing is
set in place, and wire discharge processing is started. Wire
discharge processing consists of steps of ordinary rough
processing, finish processing, and cutting edge finish
15 processing, and a cutting edge shape to be used as a press
mold is formed in the workpiece 1. Consequently, the wire
electrode changeover unit 18 changes over the electrode to
the wire electrode 2 for surface discharge processing.
Thereafter, the same surface discharge processing as in the
20 first embodiment is performed on the cutting edge side
surface of the workpiece 1 processed by the wire discharge
processing and a hard surface reforming layer is formed on
the cutting edge side surface of the workpiece 1.

Fig. 7 explains the electrode movement in the second
25 embodiment of the invention. Fig. 7 (a) explains wire

discharge processing, and Fig. 7 (b) explains surface discharge processing. In the wire discharge processing in Fig. 7 (a), the locus move control unit 13 provided in the NC unit 12 drives and controls the X-table 6 and Y-table 7 according to the electrode path information preliminarily created by the CAM device 14 for generating electrode move locus, moves the wire electrode 16 for wire discharge processing and workpiece 1 relatively in the horizontal direction, and processes the workpiece 1 into a cutting edge shape. In the surface discharge processing in Fig. 7 (b), it is required to provide a control such that the wire electrode 2 for surface discharge processing shall move along the cutting edge shape 1b of the workpiece 1. In this case, in the same manner as in the ordinary finish processing of wire discharge processing, the locus move control unit 13 provided in the NC unit 12 drives and controls the X-table 6 and Y-table 7 according to the electrode path information preliminarily created by the CAM device 14 for generating electrode move locus, moves the wire electrode 2 for surface discharge processing and workpiece 1 relatively in the horizontal direction, and controls the locus move of the wire electrode 2 for surface discharge processing so as to copy the cutting edge profile of the workpiece 1.

Thus, by processing the cutting edge portion of the workpiece 1 by wire discharge processing, and performing

surface discharge processing so as to copy the cutting edge shape after processing of the cutting edge side portion 1b, a hard surface reforming layer is formed in the cutting edge side portion 1b, and therefore the mold life can be extended 5 substantially same as in the first embodiment. Further, since the removal process of the workpiece 1 and the surface discharge processing can be done in the same preparatory step, the preparation time for processing can be shortened substantially.

10 The change over of the wire electrode 16 for wire discharge processing and the wire electrode 2 for surface discharge processing may be performed automatically by the wire electrode changeover unit 18. On the other hand, the change over of the wire discharge processing and surface 15 discharge processing may be performed manually by an operator, or by a running system for wire electrode 16 for wire discharge processing and a running system for wire electrode 2 for surface discharge processing provided independently.

20 INDUSTRIAL APPLICABILITY

The surface discharge processing method and apparatus and surface discharge processing electrode of the invention are suited to be used in surface discharge processing for forming a surface reforming layer on the surface of a 25 workpiece.

CLAIMS

1. A surface discharge processing method of generating an electric discharge between an electrode and a workpiece and thereby forming a surface reforming layer on the surface
5 of said workpiece,

wherein said electrode is a wire electrode composed of a core wire made of ductile material, and a surface discharge processing material made of a surface reforming material adhered to said core wire or a raw material for
10 the surface reforming material.

2. The surface discharge processing method according to claim 1, wherein a recess is formed in said core wire, and said surface discharge processing material is adhered to
15 this recess.

3. The surface discharge processing method according to claim 2, wherein the recess formed in said core wire is spiral in shape.

20

4. The surface discharge processing method according to claim 1, wherein a processing program for performing the surface discharge processing is the processing program for wire discharge processing employed in a preparatory step
25 of surface discharge processing.

TECHNICAL DRAWING

5. A surface discharge processing method of generating an electric discharge between an electrode and a workpiece thereby forming a surface reforming layer on the surface of said workpiece,

5 wherein a first wire electrode for removal processing by discharge, and a second wire electrode for surface discharge processing composed of a core wire made of ductile material, and a surface discharge processing material made of a surface reforming material adhered to this core wire
10 or a raw material for the surface reforming material are changed over, and the processing is done by combination of removal processing of said workpiece, and surface discharge processing for reforming the surface of the processed side formed by this removal process.

15

6. A surface discharge processing apparatus which generates an electric between an electrode and a workpiece thereby forming a surface reforming layer on the surface of said workpiece, said surface discharge processing
20 apparatus comprising:

a wire electrode as said electrode; and
a wire electrode feeder which feeds said wire electrode to said workpiece during surface discharge processing,
wherein said wire electrode is composed of a core wire
25 made of ductile material, and a surface discharge processing

00000000000000000000000000000000

material made of a surface reforming material adhered to said core wire or a raw material for the surface reforming material.

5 7. The surface discharge processing apparatus according to claim 6, wherein a recess is formed in said core wire, and said surface discharge processing material is adhered to this recess.

10 8. The surface discharge processing apparatus according to claim 7, wherein the recess formed in said core wire is spiral in shape.

9. The surface discharge processing apparatus according
15 to claim 6, wherein the processing program for performing the surface discharge processing is the processing program for wire discharge processing employed in a preparatory step of surface discharge processing.

20 10. A surface discharge processing apparatus which generates an electric discharge between a surface discharge processing electrode and a workpiece thereby forming a surface reforming layer on a surface of said workpiece, said surface discharge processing apparatus comprising:

25 a first wire electrode for removal processing by an

electric discharge;

a second wire electrode for surface discharge processing composed of a core wire made of ductile material, and a surface discharge processing material made of a surface reforming material adhered to said core wire or a raw material for the surface reforming material;

a wire electrode feeder which feeds said first wire electrode and second wire electrode to said workpiece during the processing; and

10 a wire electrode changeover unit which can select said first wire electrode when removal processing is to be performed or select said second wire electrode when surface discharge processing is to be performed.

15 11. A surface discharge processing electrode used in surface discharge processing for forming a surface reforming layer on a surface of a workpiece by discharge energy,

wherein said surface discharge processing electrode is a wire electrode composed of a core wire made of ductile material, and a surface discharge processing material made of a surface reforming material adhered to said core wire or a raw material for the surface reforming material.

12. The surface discharge processing electrode according to claim 11, wherein a recess is formed in said core wire, and said surface discharge processing material is adhered to this recess.

5

13. The surface discharge processing electrode according to claim 12, wherein the recess formed in said core wire is spiral in shape.

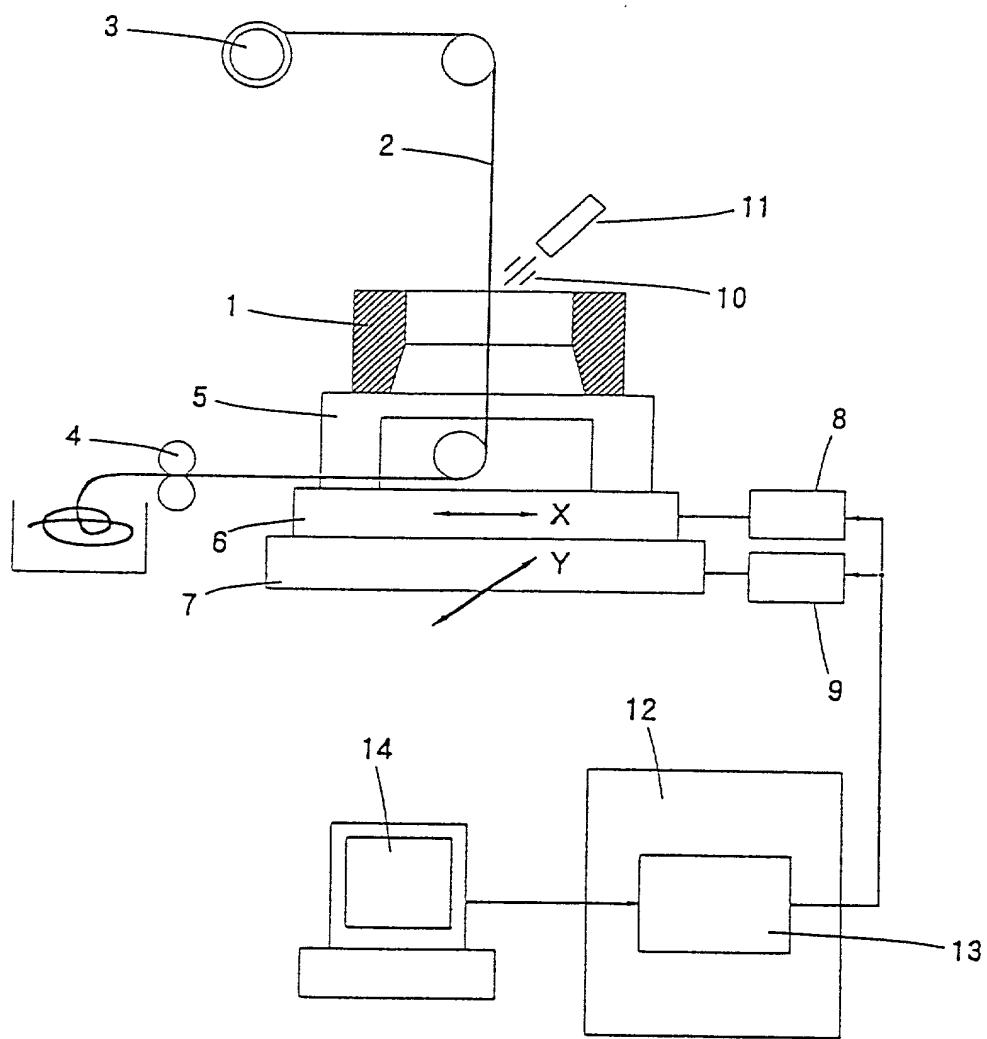


ABSTRACT

A surface discharge processing apparatus generates an electric discharge between an electrode and a workpiece (1) thereby forming a surface reforming layer on the surface 5 of the workpiece. The apparatus comprises a wire electrode (2) for surface discharge processing used as the surface discharge processing electrode, and a wire electrode feeder composed of a feed reel (3) for feeding this wire electrode (2) for surface discharge processing to the workpiece (1), 10 and a takeup reel (4) in addition to the conventional components. The wire electrode (2) is composed of a core wire (2a) made of ductile material, and a surface discharge processing material (2b) made of a surface reforming material adhered to this core wire or a raw material for the surface 15 reforming material.

00000000000000000000000000000000

FIG.1

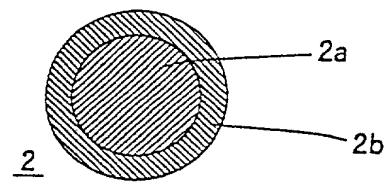


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FIG.2

(a)



(b)

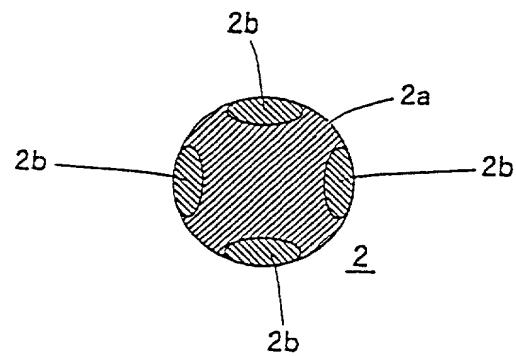
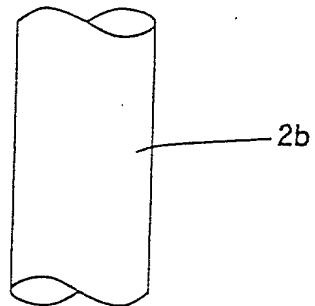
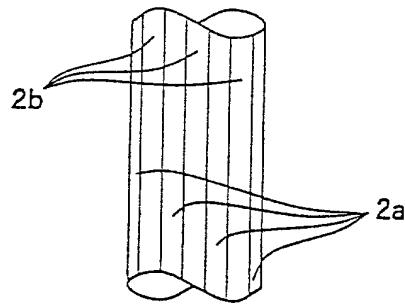


FIG.3

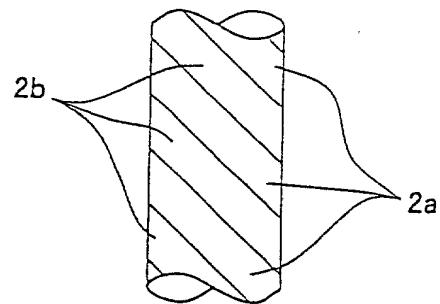
(a)



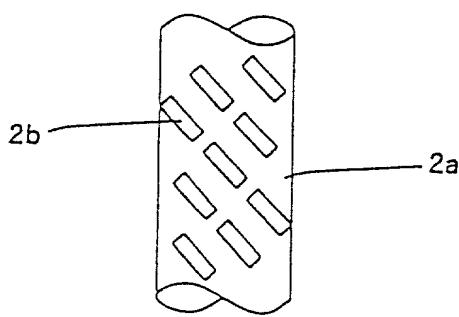
(b)



(c)



(d)



(e)

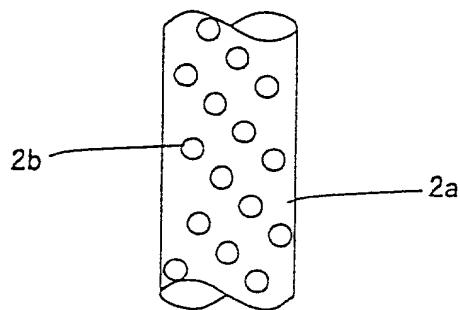


FIG.4

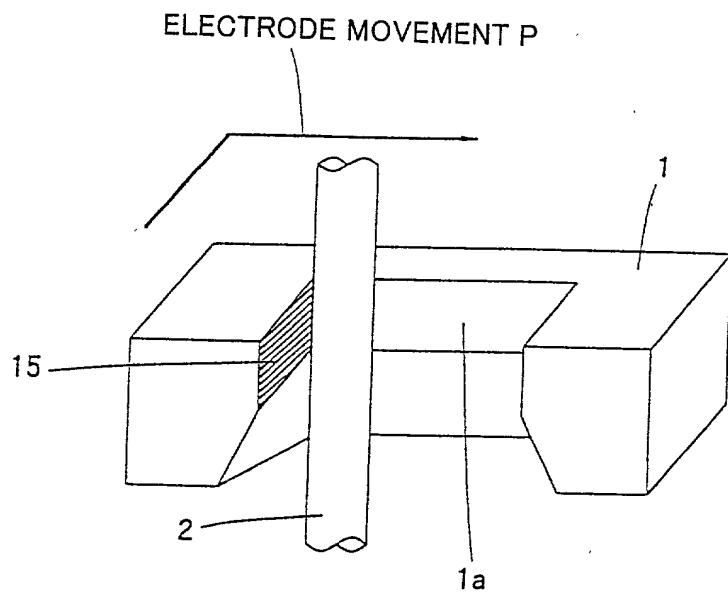
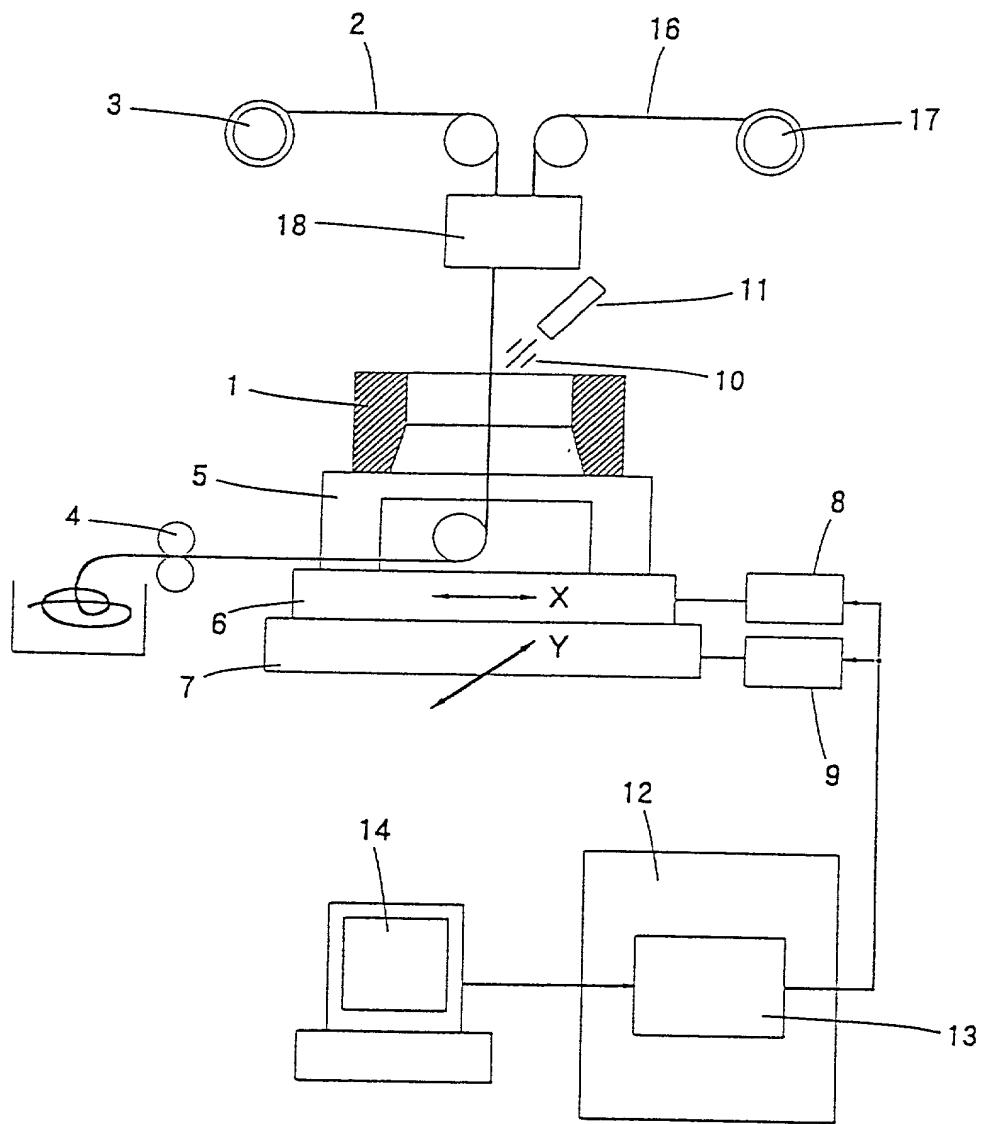


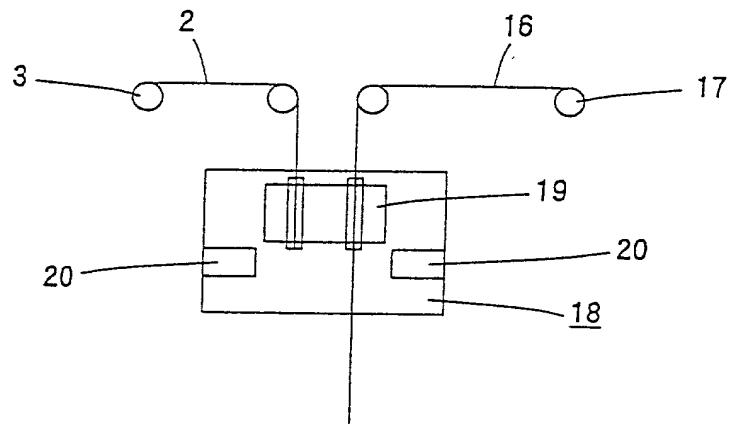
FIG.5



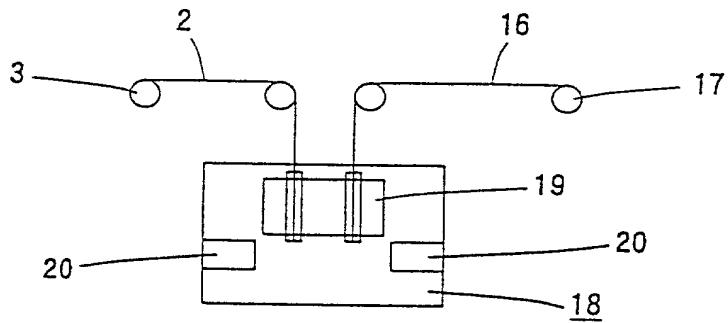
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FIG.6

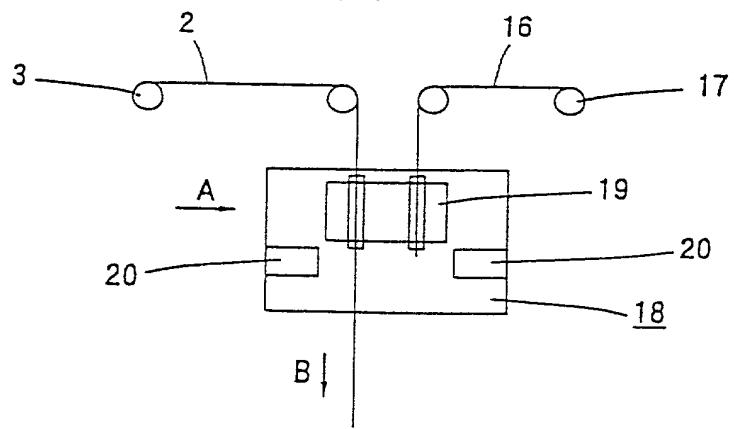
(a)



(b)



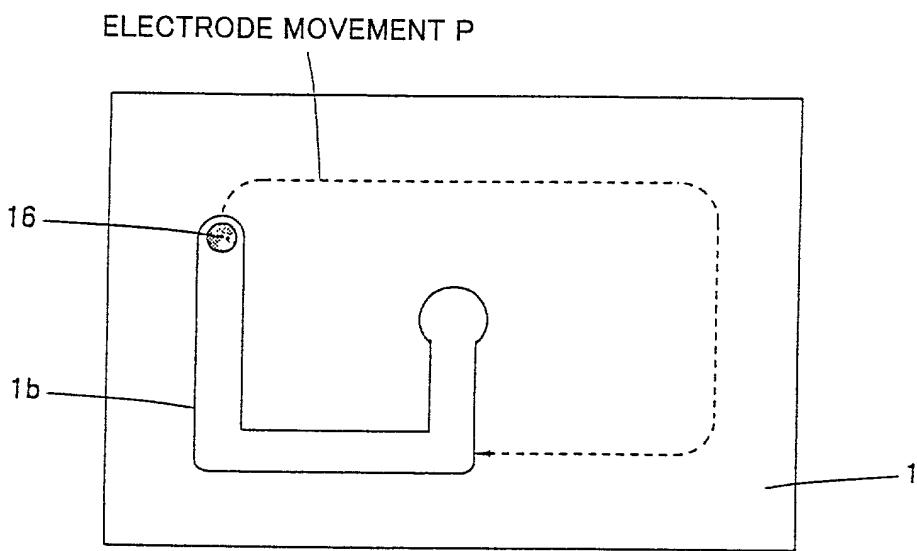
(c)



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FIG.7

(a)



(b)

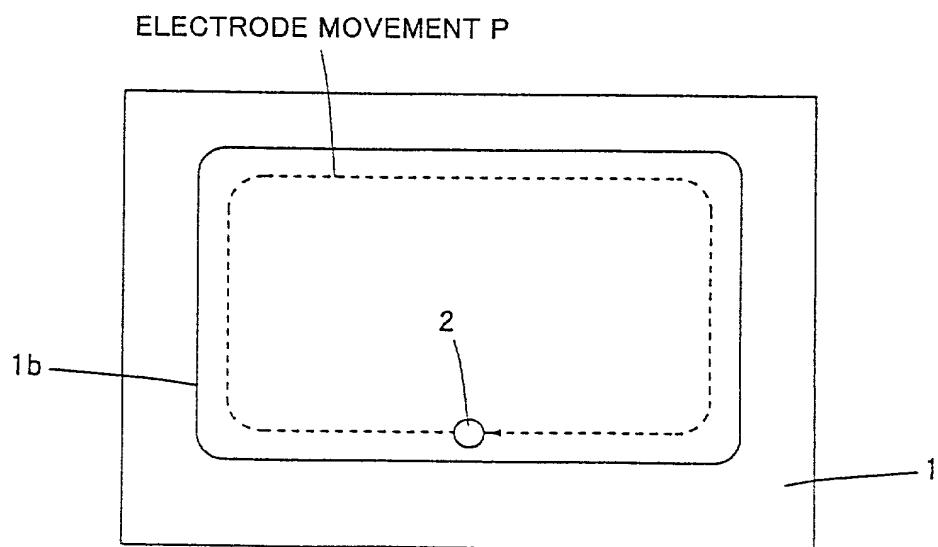
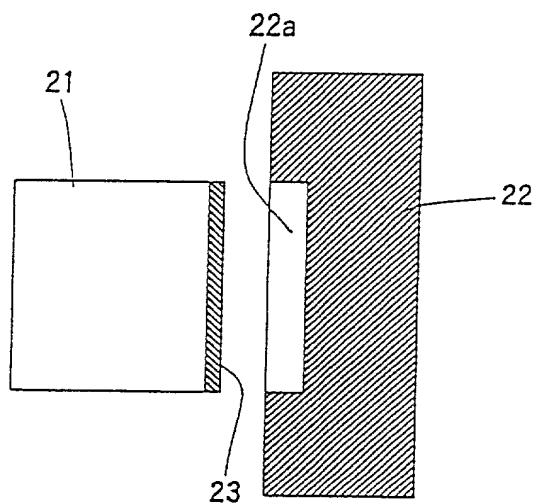
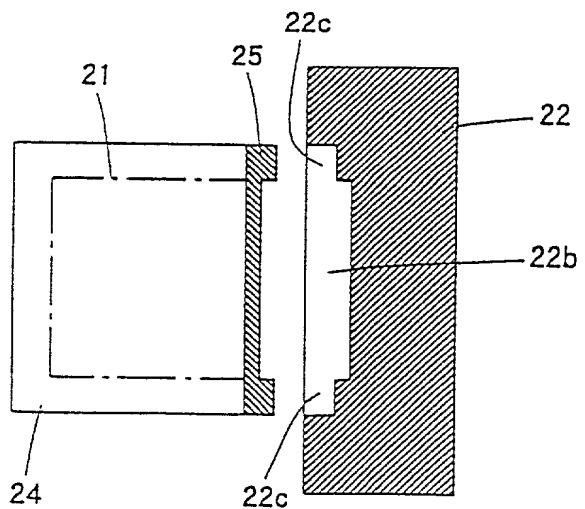


FIG.8

(a)



(b)



Declaration and Power of Attorney for Patent Application

特許出願宣言書

Japanese Language Declaration

私は、下欄に氏名を記載したと明として、以下の通り宣言する：

私の住所、郵便の宛先および国籍は、下欄に氏名に続けて記載したとおりであり。

名前は発明に關し、請求の範囲に記載した特許を求める主権の本來の、最初にして唯一の発明者である（一人の氏名のみが下欄に記載されている場合）か、もしくは本來の、最初にして共同の発明者である（複数の氏名が下欄に記載されている場合）と同じ。

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

METHOD AND APPARATUS FOR SURFACE DISCHARGE PROCESSING, AND AN ELECTRODE FOR SURFACE DISCHARGE PROCESSING

the specification of which
(check one)

is attached hereto.

was filed on _____ as

Application Serial No. _____

and was amended on _____
(if applicable)

その明細書を
(該当するほうに印を付す)

ここに添付する。

日に出願番号

第 _____

号として提出し、

日に修正した。

(該当する場合)

私は、前記のとおり修正した請求の範囲を含む前記明細書の内容を検討し、理解したことと陳述する。

私は、連邦規則法典第37部第1章第56条(a)項に従い、本願の審査に所要の情報を開示すべき義務を有することを認めらる。

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

Japanese Language Declaration

私は、合衆国法典第35部第119条にもとづく下記の外国特許出願または発明者証出願の外国優先権利益を主張し、さらに優先権の主張に係わる基礎出願の出願日前の出願日を有する外国特許出願または発明者証出願を以下に明記する：

Prior foreign applications

先の外国出願

			Priority claimed	
			優先権の主張	
(Number) (番号)	(Country) (国名)	(Day/Month/Year Filed) (出願の年月日)	<input type="checkbox"/> Yes あり	<input type="checkbox"/> No なし
(Number) (番号)	(Country) (国名)	(Day/Month/Year Filed) (出願の年月日)	<input type="checkbox"/> Yes あり	<input type="checkbox"/> No なし
(Number) (番号)	(Country) (国名)	(Day/Month/Year Filed) (出願の年月日)	<input type="checkbox"/> Yes あり	<input type="checkbox"/> No なし
(Number) (番号)	(Country) (国名)	(Day/Month/Year Filed) (出願の年月日)	<input type="checkbox"/> Yes あり	<input type="checkbox"/> No なし
(Number) (番号)	(Country) (国名)	(Day/Month/Year Filed) (出願の年月日)	<input type="checkbox"/> Yes あり	<input type="checkbox"/> No なし

私は、合衆国法典第35部第120条にもとづく下記の合衆国特許出願の利益を主張し、本願の請求の範囲各項に記載の主題が合衆国法典第35部第112条第1項に規程の様式で先の合衆国出願に開示されていない限りにおいて、先の出願の出願日と本願の国内出願日またはPCT国際出願日の間に公表された連邦規則法典第37部第1章第56条(a)項に記載の所要の情報を開示すべき義務を有することを認める。

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

PCT/JP99/02379	7/May/1999	Pending
(Application Serial No.) (出願番号)	(Filing Date) (出願日)	(現況) (特許済み、係属中、放棄済み) (Status) (patented, pending, abandoned)

(Application Serial No.) (出願番号)	(Filing Date) (出願日)	(現況) (特許済み、係属中、放棄済み) (Status) (patented, pending, abandoned)
------------------------------------	------------------------	--

私は、ここに自己の知識にもとづいて行った陳述がすべて真実であり、自己の有する情報および信ずるところに従つて行った陳述が真実であると信じ、さらに故意に虚偽の陳述等を行った場合、合衆国法典第18部第1001条により、罰金もしくは禁錮に処せられるか、またはこれらの刑が併科され、またかかる故意による虚偽の陳述が本願ないし本願に対して付与される特許の有効性を損なうことがあることを認識して、以上の陳述を行ったことを宣言する。

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Japanese Language Declaration

責任状： 私は、下記免明者として、以下の代理人をここに選任し、本願の手続きを行ふこと並びにこれに関する一切の行為を特許商標局に対して行ふことを委任する。
(代理人氏名及び登録番号を明記のこと)

POWER OF ATTORNEY As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith (list name and registration number)

③ I hereby appoint John H. Mian, Reg. No. 18,879; Donald E. Zinn, Reg. No. 19,046; Thomas J. Macpeak, Reg. No. 19,292; Robert J. Seas, Jr., Reg. No. 21,092; Darryl Mexic, Reg. No. 23,063; Robert V. Sloan, Reg. No. 22,775; Peter O. Olexy, Reg. No. 24,513; J. Frank Osha, Reg. No. 24,625; Waddell A. Biggart, Reg. No. 24,661; Robert G. McMorrow, Reg. No. 19,093; Louis Gubinsky, Reg. No. 24,835; Neil B. Siegel, Reg. No. 25,200; David J. Cushing, Reg. No. 28,703; John R. Inge, Reg. No. 26,916; Joseph J. Ruch, Jr., Reg. No. 26,577; Sheldon I. Landsman, Reg. No. 25,430; Richard C. Turner, Reg. No. 29,710; Howard L. Bernstein, Reg. No. 25,665; Alan J. Kasper, Reg. No. 25,426; Kenneth J. Burchfiel, Reg. No. 31,333; Gordon Kit, Reg. No. 30,764; Susan J. Mack, Reg. No. 30,951; Frank L. Bernstein, Reg. No. 31,484; Mark Boland, Reg. No. 32,197; William H. Mandir, Reg. No. 32,156; Scott M. Daniels, Reg. No. 32,562; Brian W. Hannon, Reg. No. 32,778; Abraham J. Rosner, Reg. No. 33,276; Bruce E. Kramer, Reg. No. 33,725; Paul F. Neils, Reg. No. 33,102; and Brett S. Sylvester, Reg. No. 32,765, my attorneys to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith, and request that all correspondence about the application be addressed to SUGHRUE, MION, ZINN, MACPEAK & SEAS, PLLC, 2100 Pennsylvania Avenue, N.W., Washington, D.C. 20037-3202.

書類の送付先：

Send Correspondence to:

SUGHRUE, MION, ZINN, MACPEAK & SEAS
2100 Pennsylvania Avenue, N.W., Washington, D.C. 20037

直通電話連絡先： (名前及び電話番号)

Direct Telephone Calls to: (name and telephone number)

(202)293-7060

唯一の又は第一の発明者の氏名	Full name of sole or first inventor Kazunobu FUJIKAWA	
同発明者の署名	日付	Inventor's signature Date Kazunobu Fujikawa Feb. 6, 2001
住所	Residence Tokyo, Japan JPX	
国籍	Citizenship Japanese	
郵便の宛先	Post office address c/o Mitsubishi Denki Kabushiki Kaisha	
	2-3, Marunouchi 2-chome Chiyoda-ku, TOKYO 100-8310 JAPAN	
第二の共同発明者の氏名 (該当する場合)	Full name of second joint inventor, if any Akihiro GOTO	
同第二発明者の署名	日付	Second inventor's signature Date Akihiro Goto Feb. 6, 2001
住所	Residence Tokyo, Japan JPX	
国籍	Citizenship Japanese	
郵便の宛先	Post office address c/o Mitsubishi Denki Kabushiki Kaisha	
	2-3, Marunouchi 2-chome Chiyoda-ku, TOKYO 100-8310 JAPAN	

(第三又はそれ以後の共同発明者に対して同様な情報
および署名を提供すること。)

(Supply similar information and signature for third and
subsequent joint inventors.)